

EAST Search History

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L1	203	(715/243).CCLS.	USPAT	OR	OFF	2008/03/04 13:02
L2	767	(715/255).OCLS.	USPAT	OR	OFF	2008/03/04 13:02
S173	526	"structured part"	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2008/03/04 11:33
S174	68	"structured part" and list	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2008/03/04 11:33
S175	587	simulation and parts and list and manufacture and price and size and shape	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2008/03/04 11:33
S176	476	simulation and parts and list and semiconductor and size and price	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2008/03/04 11:33
S177	425	"parts list" and circuit and price	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/03/04 11:33
S178	90	"parts list" and simulation and price	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/03/04 11:33
S179	1	"compatibility prediction" and simulation	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/03/04 11:33
S180	6	"compatibility prediction"	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/03/04 11:33
S181	106	prediction and "parts list" and simulation	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/03/04 11:33

S182	2	"20010014836"	US_PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/03/04 11:33
S183	2	"6110213".pn.	US_PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/03/04 11:33
S184	2	"20010014836"	US_PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2008/03/04 11:33
S185	1739	715/530	US_PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2008/03/04 11:33
S186	13651	simulation and parts and list	US_PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2008/03/04 11:33
S187	15586	"parts list"	US_PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/03/04 11:33
S188	4643	"parts list" and circuit	US_PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/03/04 11:33
S189	8618	705/26	US_PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/03/04 11:33
S190	3158	716/1	US_PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/03/04 11:33
S191	512	703/20	US_PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/03/04 11:33
S192	13805	prediction and part and simulation	US_PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/03/04 11:33

S193	526	"structured part"	US_PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2008/03/04 11:33
S194	58	"structured part" and list	US_PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2008/03/04 11:33
S195	587	simulation and parts and list and manufacture and price and size and shape	US_PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2008/03/04 11:33
S196	476	simulation and parts and list and semiconductor and size and price	US_PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2008/03/04 11:33
S197	425	"parts list" and circuit and price	US_PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/03/04 11:33
S198	90	"parts list" and simulation and price	US_PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/03/04 11:33
S199	1	"compatibility prediction" and simulation	US_PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/03/04 11:33
S200	6	"compatibility prediction"	US_PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/03/04 11:33
S201	106	prediction and "parts list" and simulation	US_PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/03/04 11:33
S202	2	"20010014836"	US_PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/03/04 11:33
S203	2	"6110213".pn.	US_PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/03/04 11:33

S204	1126828	assembly and parts	US_PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2008/03/04 11:33
S205	504816	assembly and parts and (@ad<"20000208" or @rlad<"20000208")	US_PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2008/03/04 11:33
S206	9303	"assembly parts" and parts and (@ad<"20000208" or @rlad<"20000208")	US_PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2008/03/04 11:33
S207	14	"assembly parts" and "parts information" and (@ad<"20000208" or @rlad<"20000208")	US_PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2008/03/04 11:33
S208	39510	assembly and parts and (@ad<"20000208" or @rlad<"20000208") and (update or replace) and (function or purpose)	US_PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2008/03/04 11:33
S209	8877	assembly and parts and (@ad<"20000208" or @rlad<"20000208") and (update or replace) and (function or purpose) and name	US_PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2008/03/04 11:33
S210	6264	assembly and parts and (@ad<"20000208" or @rlad<"20000208") and (update or replace) and (function or purpose) and name and storage	US_PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2008/03/04 11:33
S211	6013	assembly and parts and (@ad<"20000208" or @rlad<"20000208") and (update or replace) and function and name and storage	US_PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2008/03/04 11:33
S212	1	assembly and "structured parts" and (@ad<"20000208" or @rlad<"20000208") and (update or replace) and function and name and storage	US_PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2008/03/04 11:33
S213	77	"assembly parts" and parts and (@ad<"20000208" or @rlad<"20000208") and (update or replace) and function and name and storage	US_PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2008/03/04 11:33

S214	526	"structured part"	US_PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2008/03/04 11:33
S215	58	"structured part" and list	US_PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2008/03/04 11:33
S216	587	simulation and parts and list and manufacture and price and size and shape	US_PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2008/03/04 11:33
S217	476	simulation and parts and list and semiconductor and size and price	US_PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2008/03/04 11:33
S218	425	"parts list" and circuit and price	US_PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/03/04 11:33
S219	90	"parts list" and simulation and price	US_PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/03/04 11:33
S220	1	"compatibility prediction" and simulation	US_PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/03/04 11:33
S221	6	"compatibility prediction"	US_PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/03/04 11:33
S222	106	prediction and "parts list" and simulation	US_PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/03/04 11:33
S223	2	"20010014836"	US_PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/03/04 11:33
S224	2	"6110213".pn.	US_PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/03/04 11:33

S225	2	"20010014836"	US_PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2008/03/04 11:33
S226	1	"compatibility prediction" and simulation	US_PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/03/04 11:33
S227	58	"structured part" and list	US_PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2008/03/04 11:33
S228	90	"parts list" and simulation and price	US_PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/03/04 11:33
S229	6	"compatibility prediction"	US_PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/03/04 11:33
S230	106	prediction and "parts list" and simulation	US_PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/03/04 11:33
S231	2	"20010014836"	US_PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/03/04 11:33
S232	2	"6110213".pn.	US_PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/03/04 11:33
S233	425	"parts list" and circuit and price	US_PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/03/04 11:33
S234	512	703/20	US_PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/03/04 11:33
S235	526	"structured part"	US_PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2008/03/04 11:33

S236	587	simulation and parts and list and manufacture and price and size and shape	US_PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2008/03/04 11:33
S237	476	simulation and parts and list and semiconductor and size and price	US_PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2008/03/04 11:33
S238	1739	715/530	US_PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2008/03/04 11:33
S239	13651	simulation and parts and list	US_PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2008/03/04 11:33
S240	15586	"parts list"	US_PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/03/04 11:33
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S242	8618	705/26	US_PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/03/04 11:33
S243	3158	716/1	US_PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/03/04 11:33
S244	13805	prediction and part and simulation	US_PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/03/04 11:33
S245	1126828	assembly and parts	US_PGPUB; USPAT; USOOR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2008/03/04 11:33
S246	504816	assembly and parts and (@ad<"20000208" or @rlad<"20000208")	US_PGPUB; USPAT; USOOR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2008/03/04 11:33

S247	9303	"assembly parts" and parts and (@ad<"20000208" or @rlad<"20000208")	US_PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2008/03/04 11:33
S248	14	"assembly parts" and "parts information" and (@ad<"20000208" or @rlad<"20000208")	US_PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2008/03/04 11:33
S249	39510	assembly and parts and (@ad<"20000208" or @rlad<"20000208") and (update or replace) and (function or purpose)	US_PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2008/03/04 11:33
S250	8877	assembly and parts and (@ad<"20000208" or @rlad<"20000208") and (update or replace) and (function or purpose) and name	US_PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2008/03/04 11:33
S251	6264	assembly and parts and (@ad<"20000208" or @rlad<"20000208") and (update or replace) and (function or purpose) and name and storage	US_PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2008/03/04 11:33
S252	1	assembly and "structured parts" and (@ad<"20000208" or @rlad<"20000208") and (update or replace) and function and name and storage	US_PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2008/03/04 11:33
S253	77	"assembly parts" and parts and (@ad<"20000208" or @rlad<"20000208") and (update or replace) and function and name and storage	US_PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2008/03/04 11:33
S254	6013	assembly and parts and (@ad<"20000208" or @rlad<"20000208") and (update or replace) and function and name and storage	US_PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2008/03/04 11:33
S255	526	"structured part"	US_PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2008/03/04 11:33
S256	58	"structured part" and list	US_PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2008/03/04 11:33

S257	587	simulation and parts and list and manufacture and price and size and shape	US_PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2008/03/04 11:33
S258	476	simulation and parts and list and semiconductor and size and price	US_PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2008/03/04 11:33
S259	425	"parts list" and circuit and price	US_PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/03/04 11:33
S260	90	"parts list" and simulation and price	US_PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/03/04 11:33
S261	1	"compatibility prediction" and simulation	US_PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/03/04 11:33
S262	6	"compatibility prediction"	US_PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/03/04 11:33
S263	106	prediction and "parts list" and simulation	US_PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/03/04 11:33
S264	2	"20010014836"	US_PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/03/04 11:33
S265	2	"6110213".pn.	US_PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/03/04 11:33
S266	2	"20010014836"	US_PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2008/03/04 11:33
S267	1	"compatibility prediction" and simulation	US_PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/03/04 11:33

S268	58	"structured part" and list	US_PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2008/03/04 11:33
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S270	6	"compatibility prediction"	US_PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/03/04 11:33
S271	106	prediction and "parts list" and simulation	US_PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/03/04 11:33
S272	2	"20010014836"	US_PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/03/04 11:33
S273	2	"6110213".pn.	US_PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/03/04 11:33
S274	425	"parts list" and circuit and price	US_PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/03/04 11:33
S275	512	703/20	US_PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/03/04 11:33
S276	526	"structured part"	US_PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2008/03/04 11:33
S277	587	simulation and parts and list and manufacture and price and size and shape	US_PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2008/03/04 11:33
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S286	1126828	assembly and parts	US_PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2008/03/04 11:33
S287	504816	assembly and parts and (@ad<"20000208" or @rlad<"20000208")	US_PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2008/03/04 11:33
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S291	8877	assembly and parts and (@ad< "20000208" or @rlad< "20000208") and (update or replace) and (function or purpose) and name	US_PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2008/03/04 11:33
S292	6264	assembly and parts and (@ad< "20000208" or @rlad< "20000208") and (update or replace) and (function or purpose) and name and storage	US_PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2008/03/04 11:33
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S294	77	"assembly parts" and parts and (@ad< "20000208" or @rlad< "20000208") and (update or replace) and function and name and storage	US_PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2008/03/04 11:33
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S296	1126828	assembly and parts	US_PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2008/03/04 11:33
S297	504816	assembly and parts and (@ad< "20000208" or @rlad< "20000208")	US_PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2008/03/04 11:33
S298	9303	"assembly parts" and parts and (@ad< "20000208" or @rlad< "20000208")	US_PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2008/03/04 11:33
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S301	6264	assembly and parts and (@ad<"20000208" or @rlad<"20000208") and (update or replace) and (function or purpose) and name and storage	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2008/03/04 11:33
S302	1	assembly and "structured parts" and (@ad<"20000208" or @rlad<"20000208") and (update or replace) and function and name and storage	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2008/03/04 11:33
S303	1	"compatibility prediction" and simulation	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/03/04 11:33
S304	1	"compatibility prediction" and simulation	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/03/04 11:33
S305	58	"structured part" and list	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2008/03/04 11:33
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S307	6	"compatibility prediction"	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/03/04 11:34
S308	106	prediction and "parts list" and simulation	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/03/04 11:34
S309	2	"20010014836"	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/03/04 11:34

S310	2	"6110213".pn.	US_PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/03/04 11:34
S311	2	"20010014836"	US_PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2008/03/04 11:34
S312	58	"structured part" and list	US_PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2008/03/04 11:34
S313	90	"parts list" and simulation and price	US_PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/03/04 11:34
S314	6	"compatibility prediction"	US_PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/03/04 11:34
S315	106	prediction and "parts list" and simulation	US_PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/03/04 11:34
S316	2	"20010014836"	US_PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/03/04 11:34
S317	2	"6110213".pn.	US_PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/03/04 11:34
S318	14	"assembly parts" and "parts information" and (@ad<"20000208" or @rlad<"20000208")	US_PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2008/03/04 11:34
S319	77	"assembly parts" and parts and (@ad<"20000208" or @rlad<"20000208") and (update or replace) and function and name and storage	US_PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2008/03/04 11:34

S320	476	simulation and parts and list and semiconductor and size and price	US_PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2008/03/04 11:34
S321	425	"parts list" and circuit and price	US_PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/03/04 11:34
S322	425	"parts list" and circuit and price	US_PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/03/04 11:34
S323	476	simulation and parts and list and semiconductor and size and price	US_PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2008/03/04 11:34
S324	526	"structured part"	US_PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2008/03/04 11:34
S325	587	simulation and parts and list and manufacture and price and size and shape	US_PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2008/03/04 11:34
S326	512	703/20	US_PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/03/04 11:34
S327	526	"structured part"	US_PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2008/03/04 11:34
S328	587	simulation and parts and list and manufacture and price and size and shape	US_PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2008/03/04 11:34
S329	1739	715/530	US_PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2008/03/04 11:34
S330	13651	simulation and parts and list	US_PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2008/03/04 11:34

S331	15586	"parts list"	US_PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/03/04 11:34
S332	4643	"parts list" and circuit	US_PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/03/04 11:34
S333	8618	705/26	US_PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/03/04 11:34
S334	3158	716/1	US_PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/03/04 11:34
S335	13805	prediction and part and simulation	US_PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/03/04 11:34
S336	6013	assembly and parts and (@ad<"20000208" or @rlad<"20000208") and (update or replace) and function and name and storage	US_PGPUB; USPAT; USCOR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2008/03/04 11:34

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